



Initial Product/Process Change Notification

Document #: IPCN27355Z

Issue Date: 17 May 2026

Title of Change:	Supply Resiliency : Qualification of onsemi Suzhou, China as an additional assembly & test site for DPAK & D2PAK products from Cebu										
Proposed Changed Material First Ship Date:	31 Jan 2027 or earlier if approved by customer										
Current Material Last Order Date:	N/A <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>										
Current Material Last Delivery Date:	N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.</i>										
Product Category:	Active components – Discrete components										
Contact information:	Contact your local onsemi Sales Office or Yun.Cui@onsemi.com										
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.										
Additional Reliability Data:	Contact your local onsemi Sales Office or Jutta.Xu@onsemi.com										
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 6 months prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >										
Change Category											
Category	Type of Change										
Test Flow	SEM-TF-01: Move of all or part of electrical wafer test and/or final test to a different test site.										
Equipment	SEM-EQ-02: Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.										
Process - Assembly	SEM-PA-18: Move all or parts of production to a different assembly site., SEM-PA-11: Change of mold compound / encapsulation material, SEM-PA-17: Change of specified assembly process sequence (deletion and/or additional process step)										
Description and Purpose:											
This Product Change Notification is intended to increase capacity for selected onsemi DPAK & D2PAK products by addition of site onsemi Suzhou, China as new assembly and test site, and will use GR710F green EMC as standardization at onsemi Suzhou, China.											
<table><tr><th></th><th>Before Change</th><th>After Change</th></tr><tr><td>Assembly & Final Test site</td><td>onsemi Cebu, Philippines</td><td>onsemi Cebu, Philippines onsemi Suzhou, China</td></tr><tr><td>Mold compound material change(Suzhou)</td><td>KCC: KTMCS900GM Hitachi: CEL8240HF10 Sumitomo: EME 6600CS</td><td>Hysol: GR710F</td></tr></table>				Before Change	After Change	Assembly & Final Test site	onsemi Cebu, Philippines	onsemi Cebu, Philippines onsemi Suzhou, China	Mold compound material change(Suzhou)	KCC: KTMCS900GM Hitachi: CEL8240HF10 Sumitomo: EME 6600CS	Hysol: GR710F
	Before Change	After Change									
Assembly & Final Test site	onsemi Cebu, Philippines	onsemi Cebu, Philippines onsemi Suzhou, China									
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Reason / Motivation for Change:	Source/Supply/Capacity Changes		
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device will be qualified and validated based on the same Product Specification. No anticipated impacts.		
Sites Affected:			
onsemi Sites		External Foundry/Subcon Sites	
onsemi Suzhou, China		None	
Marking of Parts/ Traceability of Change:	Keep same marking. Changed material will be identified by site code.		
Qualification Plan:			
QV DEVICE NAME: FDD86567-F085			
PACKAGE: DPAK			
RMS: 110183/110289			
Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Tj = Max rate Tj for device, bias =80% of rated V	1,008 hrs
High Temperature Gate Bias	JESD22-A108	Tj = Max rate Tj for device, Max Vgs	1,008 hrs
High Temperature Storage Life	JESD22-A103	Ta =Max rate storage temp for device	1,008 hrs
Precondition (PC)	J-STD-020, JESD22-A113	MSL1, IR reflow at 260C	-
(PC+) Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias	96 hrs
(PC+) Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig, unbiased	96 hrs
(PC+) Temp Cycling	JESD22-A104	Temp = -55°C to +150°C	1,000 cyc
(PC+) Intermittent Operating Life	MIL STD750, M 1037, AEC Q101	Ta=+25°C, deltaTj=100°C max, 2 min Ton=Toff	15000 cyc
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B120		
QV DEVICE NAME: FDB2532-SB82023A			
PACKAGE: D2PAK			
RMS: 110180/110286			
Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Tj = Max rate Tj for device, bias =80% of rated V	1,008 hrs
High Temperature Gate Bias	JESD22-A108	Tj = Max rate Tj for device, Max Vgs	1,008 hrs
High Temperature Storage Life	JESD22-A103	Ta =Max rate storage temp for device	1,008 hrs
Precondition (PC)	J-STD-020, JESD22-A113	MSL1, IR reflow at 245C	-
(PC+) Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias	96 hrs
(PC+) Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig, unbiased	96 hrs
(PC+) Temp Cycling	JESD22-A104	Temp = -55°C to +150°C	1,000 cyc
(PC+) Intermittent Operating Life	MIL STD750, M 1037, AEC Q101	Ta=+25°C, deltaTj=100°C max, 3.5 min Ton=Toff	8,572 cyc
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B120		



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Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
FDB86563-F085	#NONE	FDB2532-SB82023A
FDD86250-F085	#NONE	FDD86567-F085
FDD86380-F085	#NONE	FDD86567-F085
FDD86381-F085	#NONE	FDD86567-F085
FDD86567-F085	#NONE	FDD86567-F085
FDD4141-F085BK	#NONE	FDD86567-F085

PCN Product List Addendum for:

Customer Contact Name: Premier Farnell Dropbox

Customer Contact Email: productchangenotices@newark.com

Appendix A: Changed Products

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NWKC: PREMIER FARNELL

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
FDD86250-F085	2895710	FDD86567-F085	#NONE	
FDD86567-F085	3003953	FDD86567-F085	#NONE	